

## RX64M Group

### Initial Settings Example

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#### Introduction

This application note describes the settings that must be made after a reset of a RX64M Group microcontroller, including clock settings, disabling of peripheral functions still running after a reset, and nonexistent port settings.

#### Target Device

- RX64M Group 177- and 176-pin versions, ROM capacity: 2 MB to 4 MB
- RX64M Group 145- and 144-pin versions, ROM capacity: 2 MB to 4 MB
- RX64M Group 100-pin version, ROM capacity: 2 MB to 4 MB

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

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## 1. Specifications

The sample code makes settings to disable peripheral functions still running after a reset, nonexistent port settings, and clock settings. The description in this application note applies to the processing that occurs following power-on (cold start).

### 1.1 Disabling Peripheral Functions Still Running After a Reset

Some peripheral functions start operating immediately after power-on, and some have the module stop function disabled. The processing covered under this item disables the following functions:

EXDMAC, DMAC, DTC, standby RAM, ECCRAM, and RAM0

Note that the above processing is not performed by the sample code. As necessary, overwrite the corresponding constants to execute the processing.

### 1.2 Nonexistent Port Settings

On products with pin counts under 176 pins, it is necessary to set the pins for ports that exist on 176-pin products but not on the target device to the output mode. On 176-pin products the bits for ports 54 to 56 should be set to output, while on 100-pin products the bits for port 56 should be set to output. The sample code contains constants suitable for 176-pin products. Overwrite the constants as necessary to accommodate the actual target device.

## 1.3 Clock Settings

### 1.3.1 Overview

The procedure for making clock settings is as follows:

1. Sub-clock settings
2. Main clock settings
3. HOCO clock settings
4. PLL clock settings
5. System clock switching

By making changes to the constants defined in `r_init_clock.h`, the sample code described in this application note can be used to change the various clock settings.

The sample code sets the PLL clock as the system clock and does not use a sub-clock. Overwrite the constants as necessary to match the clocks you wish to use.

### 1.3.2 Clock Specifications Assumed in Sample Code

Table 1.1 lists the clock specifications assumed in sample code.

**Table 1.1 Clock Specifications Assumed in Sample Code**

Clock	Oscillation Frequency	Oscillation Stabilization Time	Remarks
Main clock oscillator	24 MHz	4.2 ms*2	Crystal
Sub-clock oscillator	32.768 kHz*1	1.3 s*2	For low clock
PLL clock	240 MHz (main clock $\times 1/1 \times 10$ )	—*3	
HOCO clock	20 MHz*1	—*3	

Note 1. Oscillation disabled by the sample code.

Note 2. The oscillator's stabilization time will differ due to factors such as the wiring pattern and oscillation constant of the system. To obtain the oscillation stabilization time, request an evaluation by the oscillator manufacturer of the system in which the oscillator will be used.

Note 3. See Electrical Characteristics in User's Manual: Hardware.

### 1.3.3 Clock Selection

By making changes to the constants defined in `r_init_clock.h`, the sample code described in this application note can be used to select settings such as the clock source of the system clock and whether each clock is oscillating or stopped. To determine which constants can be changed, see the listing of (user changeable) constants used by the sample code in Table 3.7 and Table 3.8.

Table 1.2 lists clock selection examples. The sample code sets the PLL clock as the system clock and does not use a sub-clock (No. 1).

**Table 1.2 Clock Selection Examples**

No.	1	2	3	4	5	6
System clock	PLL	PLL	HOCO	HOCO	Main clock	Main clock
PLL clock	Oscillating	Oscillating	Stopped	Stopped	Stopped	Stopped
Main clock	Oscillating	Oscillating	Stopped	Stopped	Oscillating	Oscillating
HOCO clock	Stopped	Stopped	Oscillating	Oscillating	Stopped	Stopped
Sub-clock	Stopped	Oscillating (using RTC)	Stopped	Oscillating (using RTC)	Stopped	Oscillating (using RTC)
Operating mode	High-speed operating mode	High-speed operating mode	High-speed operating mode	High-speed operating mode	Low-speed operating mode 1	Low-speed operating mode 1
Constants						
SEL_SYCLK	CLK_PLL	CLK_PLL	CLK_HOCO	CLK_HOCO	CLK_MAIN	CLK_MAIN
SEL_PLL	B_USE_PLL _MAIN	B_USE_PLL _MAIN	B_NOT_USE	B_NOT_USE	B_NOT_USE	B_NOT_USE
SEL_MAIN	B_USE	B_USE	B_NOT_USE	B_NOT_USE	B_USE	B_USE
SEL_HOCO	B_NOT_USE	B_NOT_USE	B_USE	B_USE	B_NOT_USE	B_NOT_USE
SEL_SUB*1	B_NOT_USE	B_NOT_USE	B_NOT_USE	B_NOT_USE	B_NOT_USE	B_NOT_USE
SEL_RTC*1	B_NOT_USE	B_USE	B_NOT_USE	B_USE	B_NOT_USE	B_USE
REG_OPCCR	OPCM_HIGH	OPCM_HIGH	OPCM_HIGH	OPCM_HIGH	OPCM_LOW_1	OPCM_LOW_1

Note 1. Set SEL\_SUB to B\_USE (use) when the sub-clock is used as the system clock, and set SEL\_RTC to B\_USE when the sub-clock is used as the RTC count source. The sub-clock oscillates when either SEL\_SUB or SEL\_RTC, or both of them, are set to B\_USE.

## 2. Operation Confirmation Conditions

The operation of the sample code referenced in this application note (Nos. 1 to 6 in table 1.2) has been confirmed under the following conditions.

**Table 2.1 Operation Confirmation Conditions**

Item	Contents	
MCU used	R5F564MLCDFC (RX64M Group)	
Operating frequency	PLL clock selected as system clock (Nos. 1 and 2 in Table 1.2) (No.1 is default setting of sample code)	Main clock: 24 MHz PLL: 240 MHz (main clock $\times 1/1 \times 10$ ) System clock (ICLK): 120 MHz (PLL $\times 1/2$ ) Peripheral module clock A (PCLKA): 120 MHz (PLL $\times 1/2$ ) Peripheral module clocks B to D (PCLKB to PCLKD): 60 MHz (PLL $\times 1/4$ ) Flash interface clock (FCLK): 60 MHz (PLL $\times 1/4$ ) External bus clock (BCLK): 60 MHz (PLL $\times 1/4$ )
	HOCO clock selected as system clock (Nos. 3 and 4 in Table 1.2)	HOCO: 20 MHz System clock (ICLK): 20 MHz (HOCO $\times 1/1$ ) Peripheral module clock A (PCLKA): 20 MHz (HOCO $\times 1/1$ ) Peripheral module clock B to D (PCLKB to PCLKD): 10 MHz (HOCO $\times 1/2$ ) Flash interface clock (FCLK): 10 MHz (HOCO $\times 1/2$ ) External bus clock (BCLK): 10 MHz (HOCO $\times 1/2$ )
	Main clock selected as system clock (Nos. 5 and 6 in Table 1.2)	Main clock: 24MHz System clock (ICLK): 750 kHz (main clock $\times 1/32$ ) Peripheral module clock A (PCLKA): 750 kHz (main clock $\times 1/32$ ) Peripheral module clock B to D (PCLKB to PCLKD): 750 kHz (main clock $\times 1/32$ ) Flash interface clock (FCLK): 750 kHz (main clock $\times 1/32$ ) External bus clock (BCLK): 750 kHz (main clock $\times 1/32$ )
Operating voltage	3.3 V	
Integrated development environment	Renesas Electronics e <sup>2</sup> studio Version: 2021-01	
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V 3.02 Compiler option The integrated development environment default settings are used.	
iodefine.h version	V 1.0A	
Endian	Little endian or big endian	
Operating mode	Single-chip mode	
Processor mode	Supervisor mode	
Sample code version	Version 1.11	
Board used	Renesas Starter Kit+ for RX64M (Product No. R0K50564MSxxxBE)	

### 3. Software

After disabling peripheral functions still running after a reset and making nonexistent port settings, the sample code makes clock settings.

#### 3.1 Disabling Peripheral Functions Still Running After a Reset

The sample code disables peripheral functions still running after a reset.

Only the peripheral modules listed below are not in the module stop state after a reset is canceled. To transition a module to the module stop state, set the corresponding module stop bit to 1 (transition to module stop state). Putting modules into the module stop state and halting functions can reduce the power consumption of the device.

In the sample code the value of the constant `MSTP_STATE_<target module name>` is 0 (`MODULE_STOP_DISABLE`), so the target module does not transition to the module stop state. To transition one or more modules to the module stop state on the target system, set the corresponding constant(s) to 1 (`MODULE_STOP_ENABLE`) in `r_init_stop_module.h`.

Table 3.1 lists the peripheral modules that are not in the module stop state after a reset.

**Table 3.1 Peripheral Modules Not in Module Stop State After a Reset**

Peripheral Module	Module Stop Setting Bit	Value After Reset	Setting When Not Using Module
EXDMAC	MSTPCRA.MSTPA29 bit	0	1
DMAC/DTC	MSTPCRA.MSTPA28 bit	(module stop state canceled)	(transition to module stop state)
Standby RAM	MSTPCRC.MSTPC7 bit		
ECCRAM	MSTPCRC.MSTPC6 bit		
RAM0	MSTPCRC.MSTPC0 bit		

## 3.2 Nonexistent Port Settings

### 3.2.1 Processing Overview

The sample code sets the bits in the PDR registers corresponding to nonexistent ports to 1 (output). When writing in byte units to PDR or PODR registers containing nonexistent ports after this function has been called, set the direction control bits corresponding to the nonexistent ports to 1 and the port output data storage bits corresponding to the nonexistent ports to 0.

Table 3.2 lists the nonexistent ports.

**Table 3.2 Nonexistent Ports**

Port Symbol	177- and 176-Pin Products	Pins	145- and 144-Pin Products	Pins	100-Pin Products	Pins
PORT0	—	—	—	—	P00 to P03	4
PORT1	—	—	P10, P11	2	P10, P11	2
PORT2	—	—	—	—	—	—
PORT3	—	—	—	—	—	—
PORT4	—	—	—	—	—	—
PORT5	P54 to P56	3	—	—	P56	1
PORT6	—	—	—	—	P60 to P67	8
PORT7	—	—	—	—	P70 to P77	8
PORT8	—	—	—	—	P80 to P83, P86, P87	6
PORT9	—	—	P94 to P97	4	P90 to P97	8
PORTA	—	—	—	—	—	—
PORTB	—	—	—	—	—	—
PORTC	—	—	—	—	—	—
PORTD	—	—	—	—	—	—
PORTE	—	—	—	—	—	—
PORTF	—	—	PF0 to PF4	5	PF0 to PF5	6
PORTG	—	—	PG0 to PG7	8	PG0 to PG7	8
PORTJ	—	—	—	—	PJ5	1

### 3.2.2 Pin Count Setting

The setting in the sample code (PIN\_SIZE=176) is for 176-pin products. The other pin counts supported by this application note are 177, 145, 144, and 100. If the pin count of the target device is other than 176, change the value of PIN\_SIZE in r\_init\_port\_initialize.h to match the target device.

### 3.3 Clock Settings

#### 3.3.1 Clock Setting Procedure

Table 3.3 lists the steps in the clock setting procedure, the processing performed in each step, and the default settings of the sample code. Using the default settings, the sample code sets the PLL clock as the main clock and turns off the HOCO and sub-clock.

**Table 3.3 Clock Setting Procedure**

Step	Processing	Details of Processing		Sample Code Default Settings
1	Sub-clock setting*2	Not used	Initializes the sub-clock control circuit.	The sub-clock is not used.
		Used	Initializes the sub-clock control circuit, sets the drive capacity, and sets in SOSCWTCR the waiting time until output of the sub-clock to the internal clock starts; then starts oscillation by the sub-clock. After this, waits for the clock oscillation stabilization waiting time*1 using hardware.	
2	Main clock setting*2	Not used	This setting is unnecessary.	The main clock is used.
		Used	Sets the main clock drive capacity and sets in MOSCWTCR the waiting time until output of the main clock to the internal clocks starts, then starts oscillation by the main clock. After this, waits for the clock oscillation stabilization waiting time*1 using hardware.	
3	HOCO clock setting*2	Not used	Turns off the HOCO power supply.	The HOCO is not used.
		Used	Sets the HOCO frequency, then starts oscillation by the HOCO clock. After this, waits for the clock oscillation stabilization waiting time*1 using hardware.	
4	PLL clock setting*2	Not used	Turns off the PLL power supply.	The PLL clock is used.
		Used	Sets the PLL input division ratio and frequency multiplication factor, then starts oscillation by the PLL clock. After this, waits for the clock oscillation stabilization waiting time*1 using hardware.	
5	Operating power control mode setting	Sets the operating power control mode according to the operating frequency and operating voltage used.		High-speed operating mode is selected.
6	Clock division ratio settings	Changes the clock division ratios.		<ul style="list-style-type: none"> <li>• ICLK and PCLKA: <math>\times 1/2</math></li> <li>• PCLKB to PCLKD, BCLK, and FCLK: <math>\times 1/4</math></li> <li>• BCLK: Output stopped</li> </ul>
7	System clock switching	Switches according to the system used.		Switches to PLL clock.

Note 1. Confirms that the appropriate bit in the oscillation stabilization flag register (OSCOVFSR) is set to 1.

Note 2. Change the values of the constants in `r_init_clock.h` as necessary to match the selection of the clocks you wish to use or not use.

### 3.4 Section Configuration

Table 3.4 lists the information of the section changed in the sample code (r01an1918\_rx64m\_clock).

To add, change, or delete sections, refer to the latest version of the RX Family CC-RX Compiler User's Manual.

**Table 3.4 Information of the Section Changed in the Sample Code (r01an1918\_rx64m\_clock)**

Section Name	Change	Address	Description
End_of_RAM	Add	0007 FFFCh	End address of the on-chip RAM
End_of_ECCRAM	Add	00FF FFFCh	End address of the ECCRAM

### 3.5 File Composition

Table 3.5 lists the files used in the sample code. Files generated by the integrated development environment are not included in this table.

**Table 3.5 Files Used in the Sample Code**

File Name	Outline	Remarks
main.c	Main processing routine	
r_init_stop_module.c	Disable peripheral functions still running after a reset	
r_init_stop_module.h	Header file of r_init_stop_module.c	
r_init_port_initialize.c	Initial nonexistent port settings	
r_init_port_initialize.h	Header file of r_init_port_initialize.c	
r_init_clock.c	Initial clock settings	
r_init_clock.h	Header file of r_init_clock.c	

### 3.6 Option-Setting Memory

Table 3.6 lists the option-setting memory configured in the sample code. When necessary, set a value suited to the user system.

**Table 3.6 Option-Setting Memory Configured in the Sample Code**

Symbol	Address	Setting Value	Contents
OFS0	0012 0068h to 0012 006Bh	FFFF FFFFh	IWDT stopped after a reset WDT stopped after a reset
OFS1	0012 006Ch to 0012 006Fh	FFFF FFFFh	Voltage monitor 0 reset disabled after a reset HOCO oscillation disabled after a reset
MDE	0012 0064h to 0012 0067h	FFFF FFFFh	Little endian

### 3.7 Constants

Table 3.7 and Table 3.8 list the (user changeable) constants used by the sample code, Table 3.9 lists the (non user changeable) constants used by the sample code, and Table 3.10 to Table 3.12 list the constants specific to each package.

**Table 3.7 Constants (User Changeable) Used by Sample Code (1/2)**

Constant Name	Setting Value	Contents
SEL_MAIN* <sup>1</sup>	B_USE	Main clock enable/disable selection B_USE: Used (main clock enabled) B_NOT_USE: Not used (main clock disabled)
MAIN_CLOCK_HZ* <sup>1</sup>	24,000,000 L	Main clock oscillator frequency (Hz)
REG_MOFCR* <sup>1</sup>	00h	Main clock oscillator drive capacity setting (setting value of MOFCR register)
REG_MOSCWTCR* <sup>1</sup>	53h	Setting value of main clock wait control register
SEL_SUB* <sup>1</sup> * <sup>2</sup>	B_NOT_USE	Sub-clock usage selection (used as system clock) B_USE: Used B_NOT_USE: Not used
SEL_RTC* <sup>1</sup> * <sup>2</sup>	B_NOT_USE	Sub-clock usage selection (used as RTC count source) B_USE: Used B_NOT_USE: Not used
SUB_CLOCK_HZ* <sup>1</sup>	32,768 L	Sub-clock oscillator frequency (Hz)
REG_SOSCWTCR* <sup>1</sup>	21h	Setting value of sub-clock wait control register
REG_RCR3* <sup>1</sup>	CL_LOW	Sub-clock oscillator drive capacity selection CL_STD: Drive capacity for standard clock CL_LOW: Drive capacity for low clock
SEL_PLL* <sup>1</sup>	B_USE_PLL_MAIN	PLL clock enable/disable selection B_USE_PLL_MAIN: Used (main clock) B_USE_PLL_HOCO: Used (HOCO) B_NOT_USE: Not used (PLL clock disabled)
REG_PLLCR* <sup>1</sup>	1300h	PLL input division ratio and frequency multiplication factor settings (setting value of PLLCR register)

Note 1. Change the settings values in r\_init\_clock.h to match the target system.

Note 2. The sub-clock oscillates when either SEL\_SUB or SEL\_RTC, or both of them, are set to B\_USE (use).

**Table 3.8 Constants (User Changeable) Used by Sample Code (2/2)**

Constant Name	Setting Value	Contents
SEL_HOCO* <sup>1</sup>	B_NOT_USE	HOCO clock enable/disable selection B_USE: Used (HOCO clock enabled) B_NOT_USE: Not used (HOCO clock disabled)
REG_HOCOCR2* <sup>1</sup>	FREQ_20MHZ	HOCO clock frequency selection FREQ_16 MHZ: 16 MHz FREQ_18 MHZ: 18 MHz FREQ_20 MHZ: 20 MHz
SEL_SYSCCLK* <sup>1</sup>	CLK_PLL	System clock clock source selection CLK_PLL: PLL CLK_HOCO: HOCO CLK_MAIN: main clock CLK_SUB: sub-clock
REG_OPCCR* <sup>1</sup>	OPCM_HIGH	Operating power control mode selection* <sup>6</sup> OPCM_HIGH: High-speed operating mode OPCM_LOW_1: Low-speed operating mode 1* <sup>4</sup> OPCM_LOW_2: Low-speed operating mode 2* <sup>5</sup>
MSTP_STATE_EXDMAC* <sup>2</sup>	MODULE_STOP_DISABLE	EXDMAC module stop state selection MODULE_STOP_DISABLE: Disable module stop MODULE_STOP_ENABLE: Transition to module stop
MSTP_STATE_DMADTC* <sup>2</sup>	MODULE_STOP_DISABLE	DMAC and DTC module stop state selection MODULE_STOP_DISABLE: Disable module stop MODULE_STOP_ENABLE: Transition to module stop
MSTP_STATE_STBYRAM* <sup>2</sup>	MODULE_STOP_DISABLE	Standby RAM module stop state selection MODULE_STOP_DISABLE: Disable module stop MODULE_STOP_ENABLE: Transition to module stop
MSTP_STATE_ECCRAM* <sup>2</sup>	MODULE_STOP_DISABLE	ECCRAM module stop state selection MODULE_STOP_DISABLE: Disable module stop MODULE_STOP_ENABLE: Transition to module stop
MSTP_STATE_RAM0* <sup>2</sup>	MODULE_STOP_DISABLE	RAM0 module stop state selection MODULE_STOP_DISABLE: Disable module stop MODULE_STOP_ENABLE: Transition to module stop
PIN_SIZE* <sup>3</sup>	176	Pin count of target device

Note 1. Change the settings values in `r_init_clock.h` to match the target system.

Note 2. Change the settings values in `r_init_stop_module.h` to match the target system.

Note 3. Change the settings values in `r_init_port_initialize.h` to match the target system.

Note 4. It is not possible to select low-speed operating mode 1 when the PLL clock is set to oscillate.

Note 5. It is not possible to select low-speed operating mode 2 when the PLL clock or HOCO is set to oscillate.

Note 6. The operating frequency range and operating voltage range differ depending on the operating mode. For details, see RX64M Group User's Manual: Hardware.

**Table 3.9 Constants (Non User Changeable) Used by Sample Code**

Constant Name	Setting Value	Contents
B_NOT_USE	0	Not used
B_USE	1	Used
B_USE_PLL_MAIN	2	The PLL clock is used. (Clock source: Main clock)
B_USE_PLL_HOCO	3	The PLL clock is used. (Clock source: HOCO clock)
CL_LOW	02h	Sub-clock: Drive capacity for low clock
CL_STD	0Ch	Sub-clock: Drive capacity for standard clock
FREQ_16MHZ	00h	HOCO frequency: 16 MHz
FREQ_18MHZ	01h	HOCO frequency: 18 MHz
FREQ_20MHZ	02h	HOCO frequency: 20 MHz
CLK_PLL	0400h	Clock source: PLL
CLK_HOCO	0100h	Clock source: HOCO
CLK_SUB	0300h	Clock source: Sub-clock
CLK_MAIN	0200h	Clock source: Main clock
REG_SCKCR*1	21C2 1222h (PLL selected) 10C1 0111h (HOCO selected) 55C5 5555h (other than the above)	Internal clock division ratio and BCLK/SDCLK pin output control settings (setting value of SCKCR register)
OPCM_HIGH	00h	Operating power control mode: High-speed operating mode
OPCM_LOW_1	06h	Operating power control mode: Low-speed operating mode 1
OPCM_LOW_2	07h	Operating power control mode: Low-speed operating mode 2
SUB_CLOCK_CYCLE	(1,000,000,000L / SUB_CLOCK_HZ)	Sub-clock cycle (ns)
FOR_CMT0_TIME	121212L	Count cycle (ns) of timer for RTC software wait cycles (CMT0) = 1/LOCO (264 kHz) ×32 (LOCO = 264 kHz (max.), PCLKB ×1/32)
MODULE_STOP_ENABLE	1	Transition to module stop state
MODULE_STOP_DISABLE	0	Cancel module stop state

Note 1. The setting value differs depending on the selected system clock clock source.

**Table 3.10 Constants for 177- and 176-Pin Products (PIN\_SIZE=177 or PIN\_SIZE=176)**

Constant Name	Setting Value	Contents
DEF_P0PDR	0x00	Port P0 direction register setting value
DEF_P1PDR	0x00	Port P1 direction register setting value
DEF_P2PDR	0x00	Port P2 direction register setting value
DEF_P3PDR	0x00	Port P3 direction register setting value
DEF_P4PDR	0x00	Port P4 direction register setting value
DEF_P5PDR	0x70	Port P5 direction register setting value
DEF_P6PDR	0x00	Port P6 direction register setting value
DEF_P7PDR	0x00	Port P7 direction register setting value
DEF_P8PDR	0x00	Port P8 direction register setting value
DEF_P9PDR	0x00	Port P9 direction register setting value
DEF_PAPDR	0x00	Port PA direction register setting value
DEF_PBPDR	0x00	Port PB direction register setting value
DEF_PCPDR	0x00	Port PC direction register setting value
DEF_PDPDR	0x00	Port PD direction register setting value
DEF_PEPDR	0x00	Port PE direction register setting value
DEF_PFPDR	0x00	Port PF direction register setting value
DEF_PGPDR	0x00	Port PG direction register setting value
DEF_PJPDR	0x00	Port PJ direction register setting value

**Table 3.11 Constants for 145- and 144-Pin Products (PIN\_SIZE=145 or PIN\_SIZE=144)**

Constant Name	Setting Value	Contents
DEF_P0PDR	0x00	Port P0 direction register setting value
DEF_P1PDR	0x03	Port P1 direction register setting value
DEF_P2PDR	0x00	Port P2 direction register setting value
DEF_P3PDR	0x00	Port P3 direction register setting value
DEF_P4PDR	0x00	Port P4 direction register setting value
DEF_P5PDR	0x00	Port P5 direction register setting value
DEF_P6PDR	0x00	Port P6 direction register setting value
DEF_P7PDR	0x00	Port P7 direction register setting value
DEF_P8PDR	0x00	Port P8 direction register setting value
DEF_P9PDR	0xF0	Port P9 direction register setting value
DEF_PAPDR	0x00	Port PA direction register setting value
DEF_PBPDR	0x00	Port PB direction register setting value
DEF_PCPDR	0x00	Port PC direction register setting value
DEF_PDPDR	0x00	Port PD direction register setting value
DEF_PEPDR	0x00	Port PE direction register setting value
DEF_PFPDR	0x1F	Port PF direction register setting value
DEF_PGPDR	0xFF	Port PG direction register setting value
DEF_PJPDR	0x00	Port PJ direction register setting value

**Table 3.12 Constants for 100-Pin Products (PIN\_SIZE=100)**

Constant Name	Setting Value	Contents
DEF_P0PDR	0x0F	Port P0 direction register setting value
DEF_P1PDR	0x03	Port P1 direction register setting value
DEF_P2PDR	0x00	Port P2 direction register setting value
DEF_P3PDR	0x00	Port P3 direction register setting value
DEF_P4PDR	0x00	Port P4 direction register setting value
DEF_P5PDR	0x40	Port P5 direction register setting value
DEF_P6PDR	0xFF	Port P6 direction register setting value
DEF_P7PDR	0xFF	Port P7 direction register setting value
DEF_P8PDR	0xCF	Port P8 direction register setting value
DEF_P9PDR	0xFF	Port P9 direction register setting value
DEF_PAPDR	0x00	Port PA direction register setting value
DEF_PBPDR	0x00	Port PB direction register setting value
DEF_PCPDR	0x00	Port PC direction register setting value
DEF_PDPDR	0x00	Port PD direction register setting value
DEF_PEPDR	0x00	Port PE direction register setting value
DEF_PFPDR	0x3F	Port PF direction register setting value
DEF_PGPDR	0xFF	Port PG direction register setting value
DEF_PJPDR	0x20	Port PJ direction register setting value

### 3.8 Functions

Table 3.13 lists the functions.

**Table 3.13 Functions**

Function Name	Outline
main	Main processing routine
R_INIT_StopModule	Disable peripheral functions still running after a reset
R_INIT_Port_Initialize	Initial nonexistent port settings
R_INIT_Clock	Initial clock settings
CGC_oscillation_main	Main clock oscillation enable
CGC_oscillation_HOCO	HOCO clock oscillation enable
CGC_oscillation_PLL	PLL clock oscillation enable
CGC_oscillation_sub	Sub-clock oscillation enable
CGC_disable_subclk	Sub-clock disable
oscillation_subclk	Sub-clock oscillation enable
resetting_wtcr_subclk	Sub-clock wait control register resetting
init_rtc	Initialization when using RTC
cmt0_wait	Software wait cycles using CMT0

### 3.9 Function Specifications

The following tables list the sample code function specifications.

<hr/>	
main	
<b>Outline</b>	Main processing routine
<b>Header</b>	None
<b>Declaration</b>	void main(void)
<b>Description</b>	Calls the settings function for disabling peripheral functions still running after a reset, the initial nonexistent port settings function, and the initial clock settings function.
<b>Arguments</b>	None
<b>Return Value</b>	None
<hr/>	
R_INIT_StopModule	
<b>Outline</b>	Disable peripheral functions still running after a reset
<b>Header</b>	r_init_stop_module.h
<b>Declaration</b>	void R_INIT_StopModule(void)
<b>Description</b>	Makes settings to transition to the module stop state.
<b>Arguments</b>	None
<b>Return Value</b>	None
<b>Remarks</b>	In the sample code, no transition to the module stop state occurs.
<hr/>	
R_INIT_Port_Initialize	
<b>Outline</b>	Initial nonexistent port settings
<b>Header</b>	r_init_port_initialize.h
<b>Declaration</b>	void R_INIT_Port_Initialize(void)
<b>Description</b>	Makes initial settings to the port direction registers corresponding to the pins of nonexistent port.
<b>Arguments</b>	None
<b>Return Value</b>	None
<b>Remarks</b>	The setting in the sample code (PIN_SIZE=176) is for 176-pin products. When writing in byte units to PDR or PODR registers containing nonexistent ports after this function has been called, set the direction control bits corresponding to the nonexistent ports to 1 and the port output data storage bits corresponding to the nonexistent ports to 0.
<hr/>	
R_INIT_Clock	
<b>Outline</b>	Initial clock settings
<b>Header</b>	r_init_clock.h
<b>Declaration</b>	void R_INIT_Clock(void)
<b>Description</b>	Makes initial clock settings.
<b>Arguments</b>	None
<b>Return Value</b>	None
<b>Remarks</b>	In the sample code processing is selected that sets the PLL clock as the system clock and does not use a sub-clock.

---

<b>CGC_oscillation_main</b>	
<b>Outline</b>	Main clock oscillation enable
<b>Header</b>	r_init_clock.h
<b>Declaration</b>	void CGC_oscillation_main (void)
<b>Description</b>	Sets the drive capacity of the main clock and sets the MOSCWTCR register, then starts oscillation of the main clock. After this, waits for the main clock oscillation stabilization waiting time using hardware.
<b>Arguments</b>	None
<b>Return Value</b>	None

---

<b>CGC_oscillation_HOCO</b>	
<b>Outline</b>	HOCO clock oscillation enable
<b>Header</b>	r_init_clock.h
<b>Declaration</b>	void CGC_oscillation_HOCO (void)
<b>Description</b>	Sets the HOCO frequency, then starts oscillation of the HOCO. After this, waits for the HOCO oscillation stabilization waiting time using hardware.
<b>Arguments</b>	None
<b>Return Value</b>	None

---

<b>CGC_oscillation_PLL</b>	
<b>Outline</b>	PLL clock oscillation enable
<b>Header</b>	r_init_clock.h
<b>Declaration</b>	void CGC_oscillation_PLL (void)
<b>Description</b>	Sets the PLL input division ratio and frequency multiplication factor, then starts oscillation of the PLL clock. After this, waits for the PLL clock oscillation stabilization waiting time using hardware.
<b>Arguments</b>	None
<b>Return Value</b>	None

---

<b>CGC_oscillation_sub</b>	
<b>Outline</b>	Sub-clock oscillation enable
<b>Header</b>	r_init_clock.h
<b>Declaration</b>	void CGC_oscillation_sub (void)
<b>Description</b>	Makes settings for using the sub-clock as the system clock or as the RTC count source, or for both.
<b>Arguments</b>	None
<b>Return Value</b>	None

---

<b>CGC_disable_subclk</b>	
<b>Outline</b>	Sub-clock disable
<b>Header</b>	r_init_clock.h
<b>Declaration</b>	void CGC_disable_subclk (void)
<b>Description</b>	Makes settings for when the sub-clock is not used as the system clock and the RTC count source.
<b>Arguments</b>	None
<b>Return Value</b>	None

---



### 3.10 Flowcharts

#### 3.10.1 Main Processing

Figure 3.1 shows the main processing.

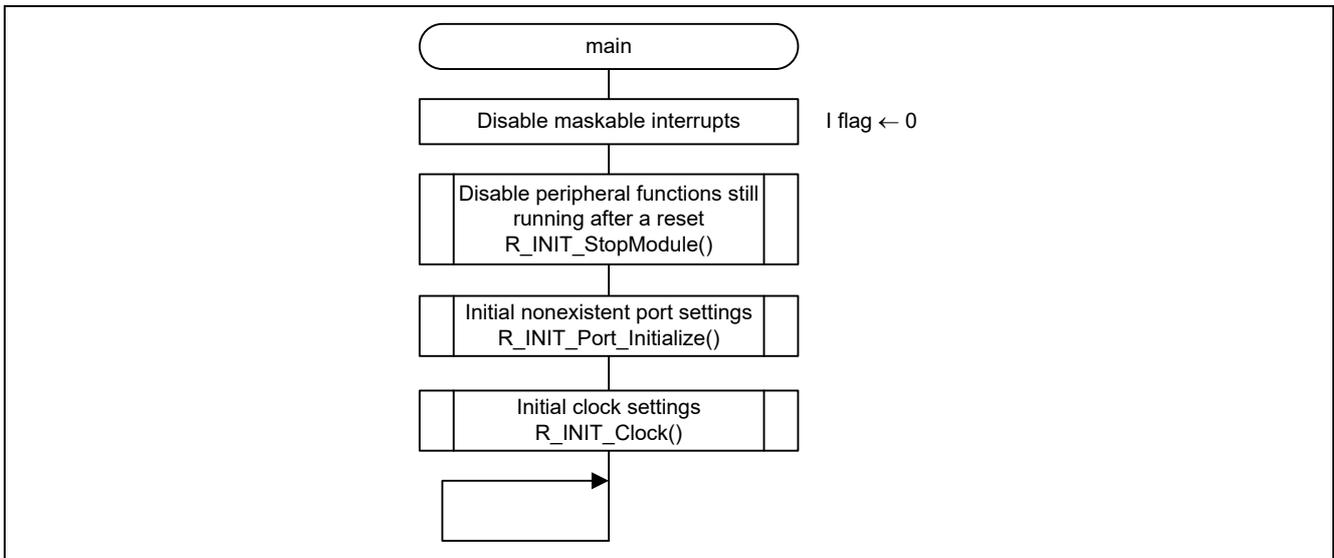
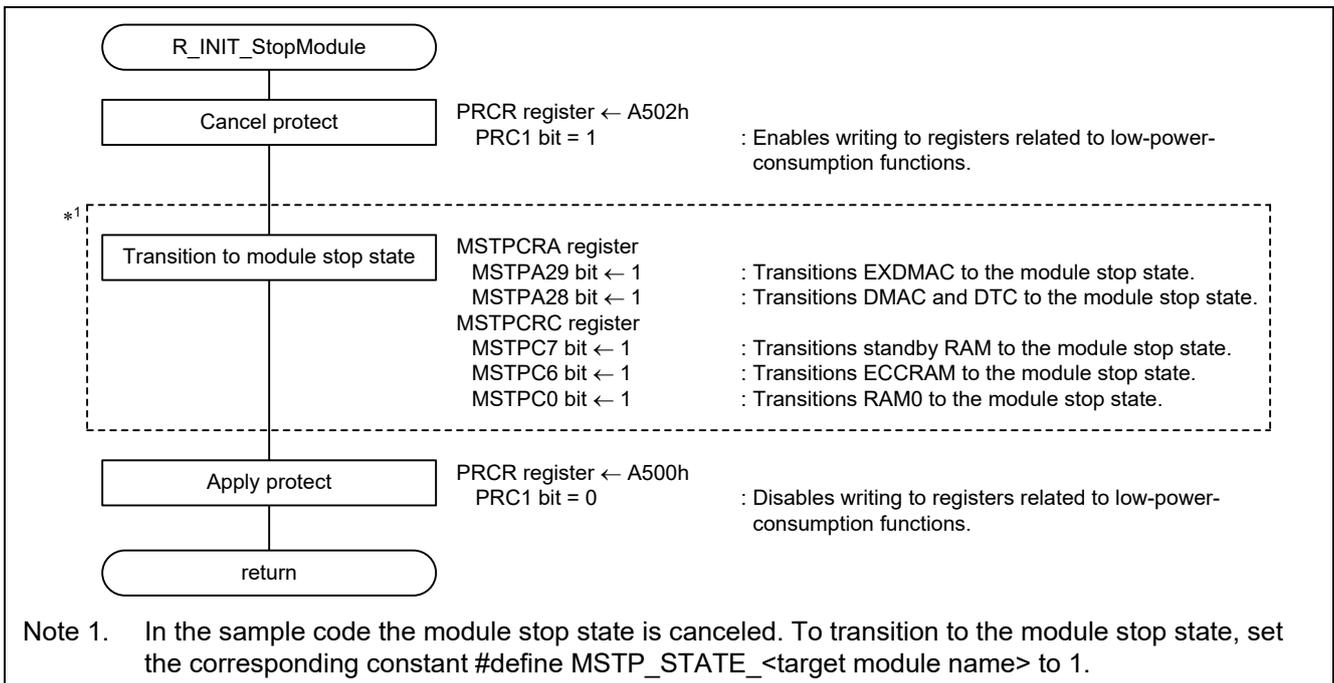


Figure 3.1 Main Processing

#### 3.10.2 Disable Peripheral Functions Still Running After a Reset

Figure 3.2 is a flowchart of the processing for disabling of peripheral functions still running after a reset.



Note 1. In the sample code the module stop state is canceled. To transition to the module stop state, set the corresponding constant #define MSTP\_STATE\_<target module name> to 1.

Figure 3.2 Disable Peripheral Functions Still Running After a Reset

### 3.10.3 Initial Nonexistent Port Settings

Figure 3.3 is a flowchart of the processing for making initial nonexistent port settings.

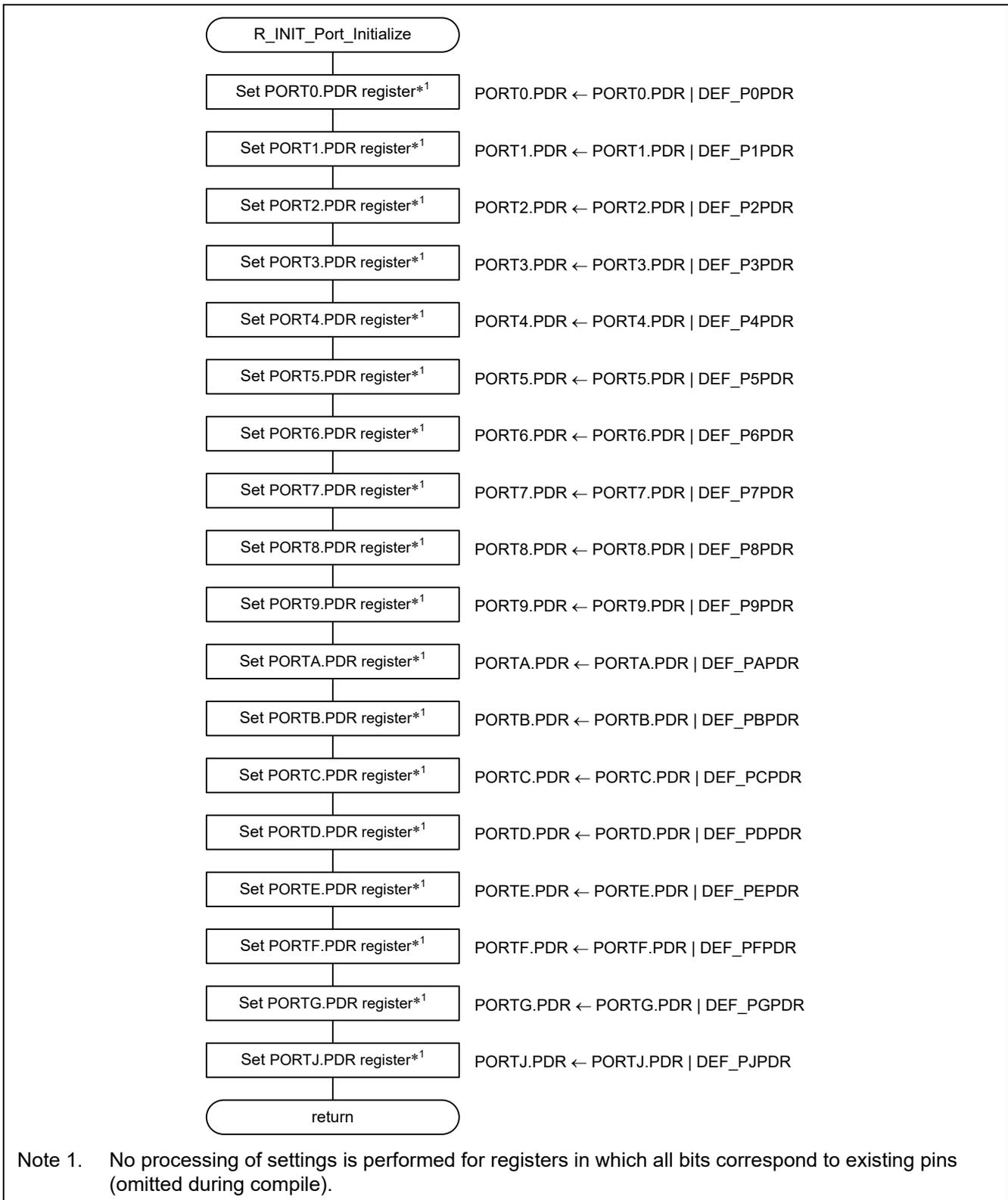
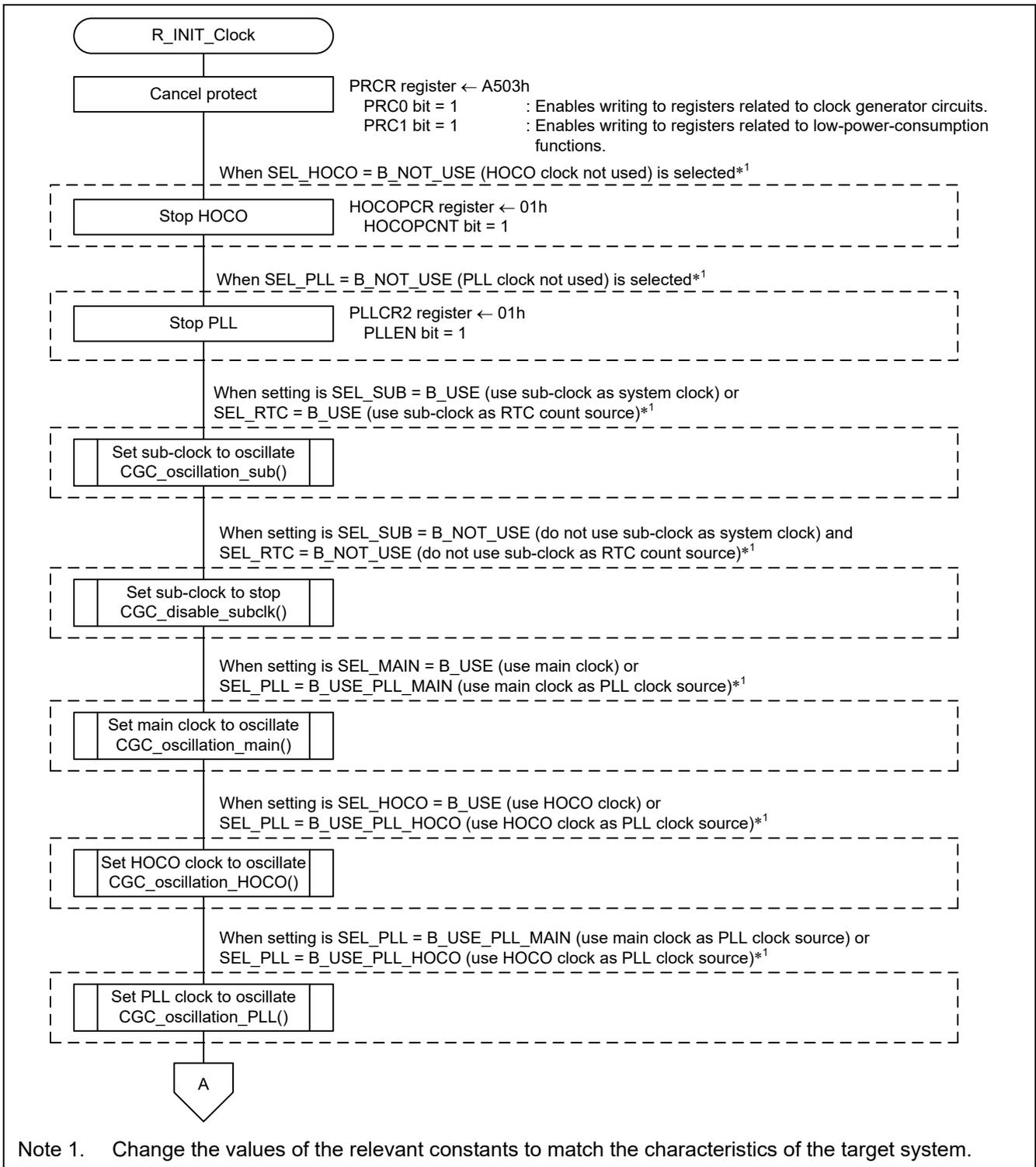


Figure 3.3 Initial Nonexistent Port Settings

**3.10.4 Initial Clock Settings**

Figure 3.4 and Figure 3.5 are flowcharts of the processing for making initial clock settings (1/2) and (2/2).



Note 1. Change the values of the relevant constants to match the characteristics of the target system.

**Figure 3.4 Initial Clock Settings (1/2)**

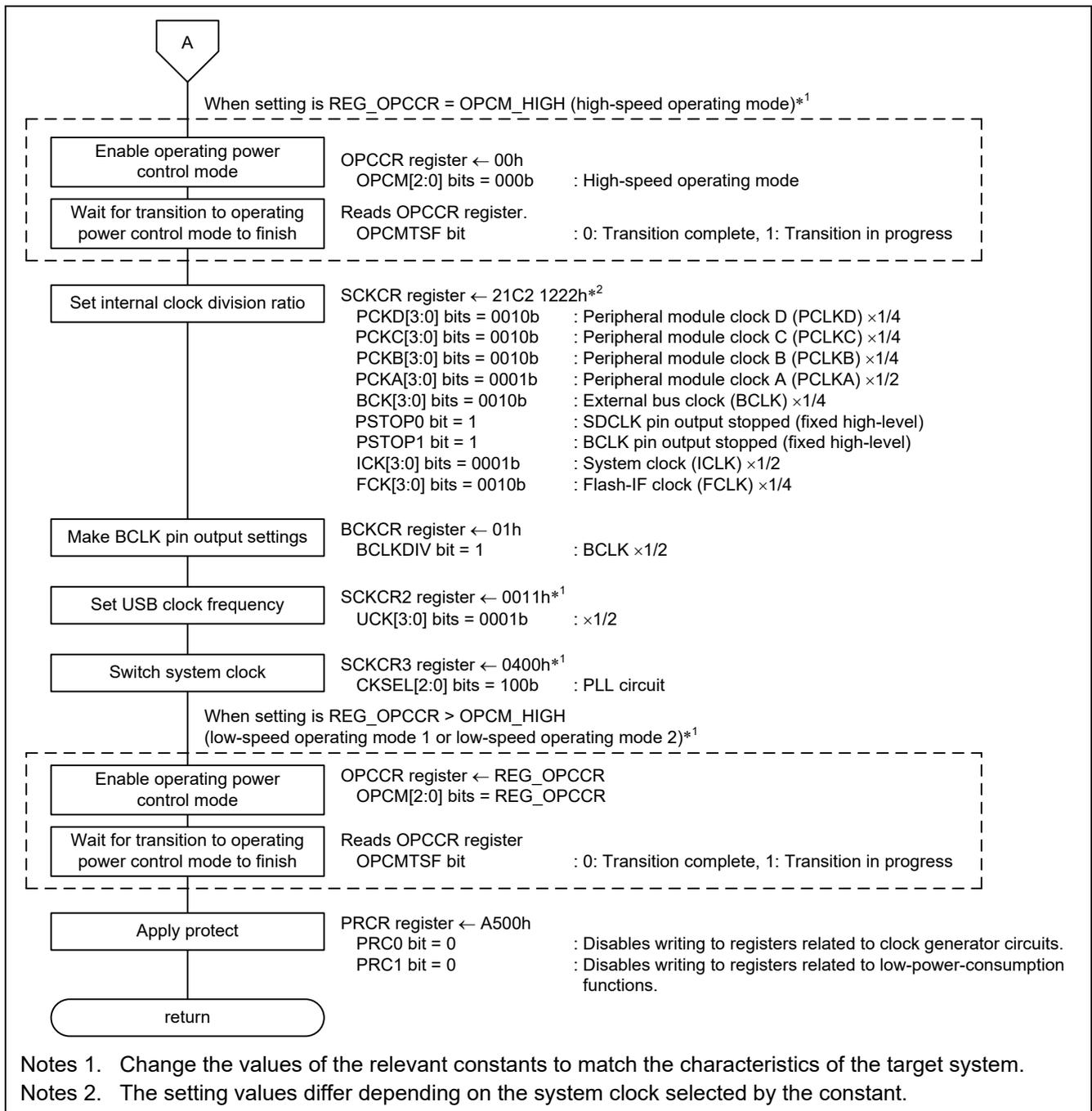


Figure 3.5 Initial Clock Settings (2/2)

### 3.10.5 Main Clock Oscillation Enable

Figure 3.6 is a flowchart of the processing for starting oscillation of the main clock.

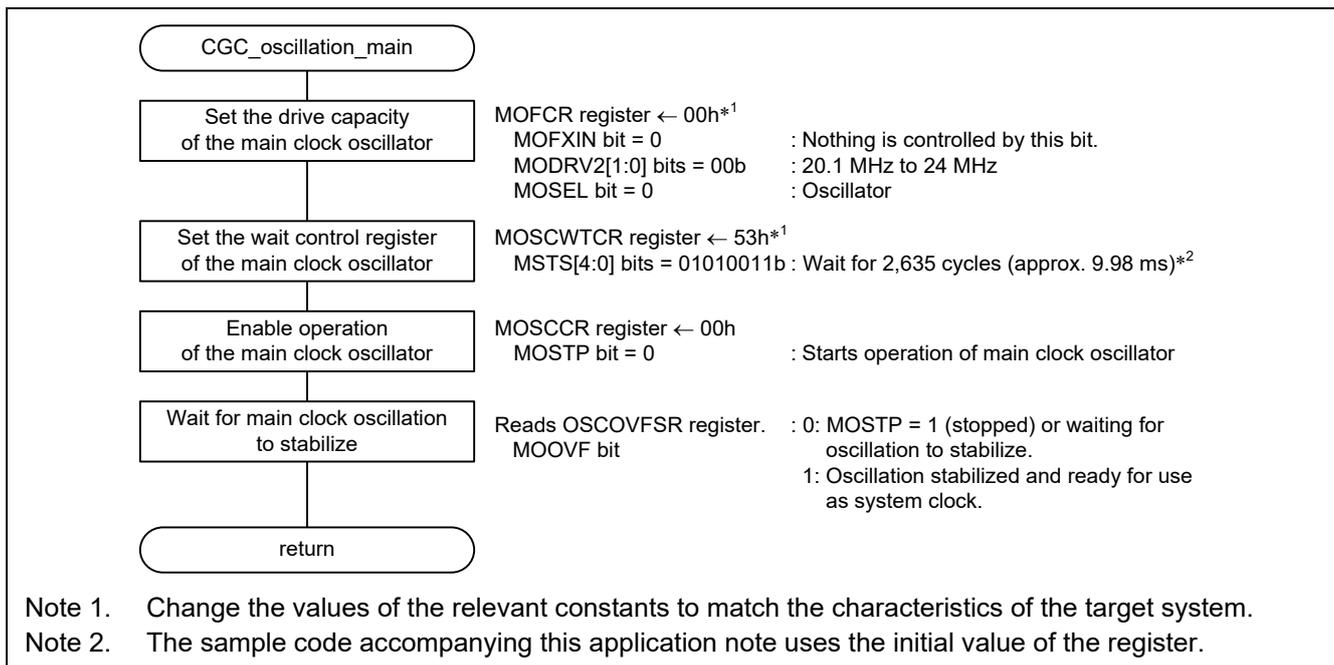


Figure 3.6 Main Clock Oscillation Enable

### 3.10.6 PLL Clock Oscillation Enable

Figure 3.7 is a flowchart of the processing for starting oscillation of the PLL clock.

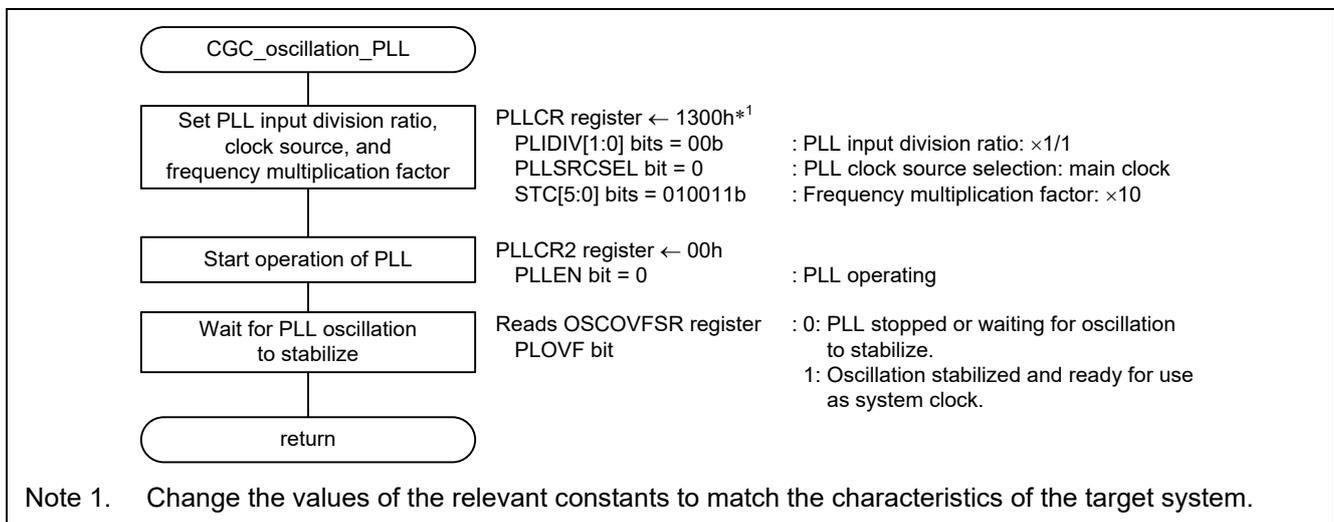


Figure 3.7 PLL Clock Oscillation Enable

### 3.10.7 HOCO Clock Oscillation Enable

Figure 3.8 is a flowchart of the processing for starting oscillation of the HOCO clock.

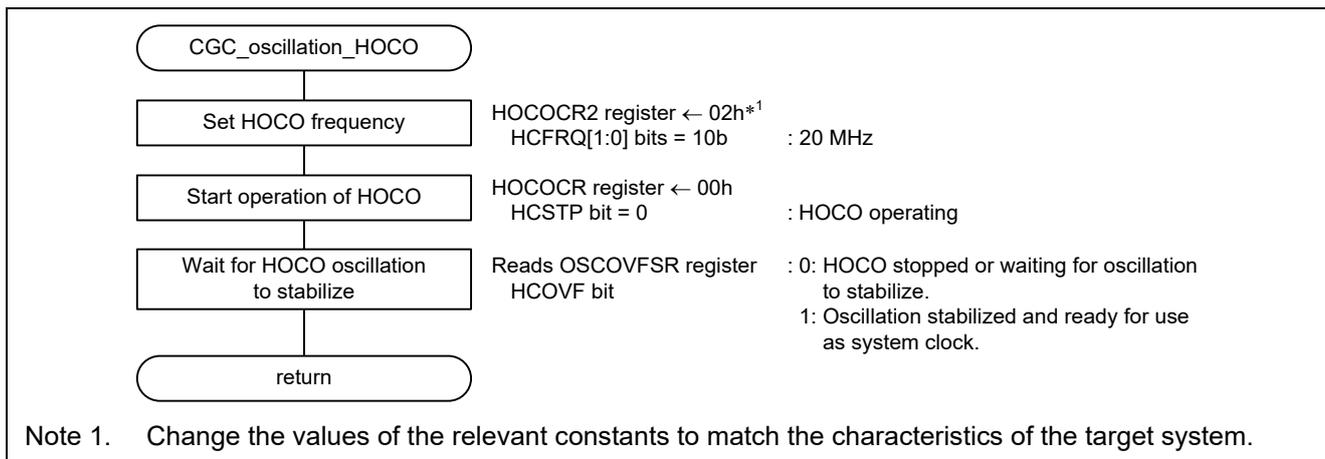


Figure 3.8 HOCO Clock Oscillation Enable

### 3.10.8 Sub-clock Oscillation Enable

Figure 3.9 and Figure 3.10 are flowcharts of the processing for starting oscillation of the sub-clock.

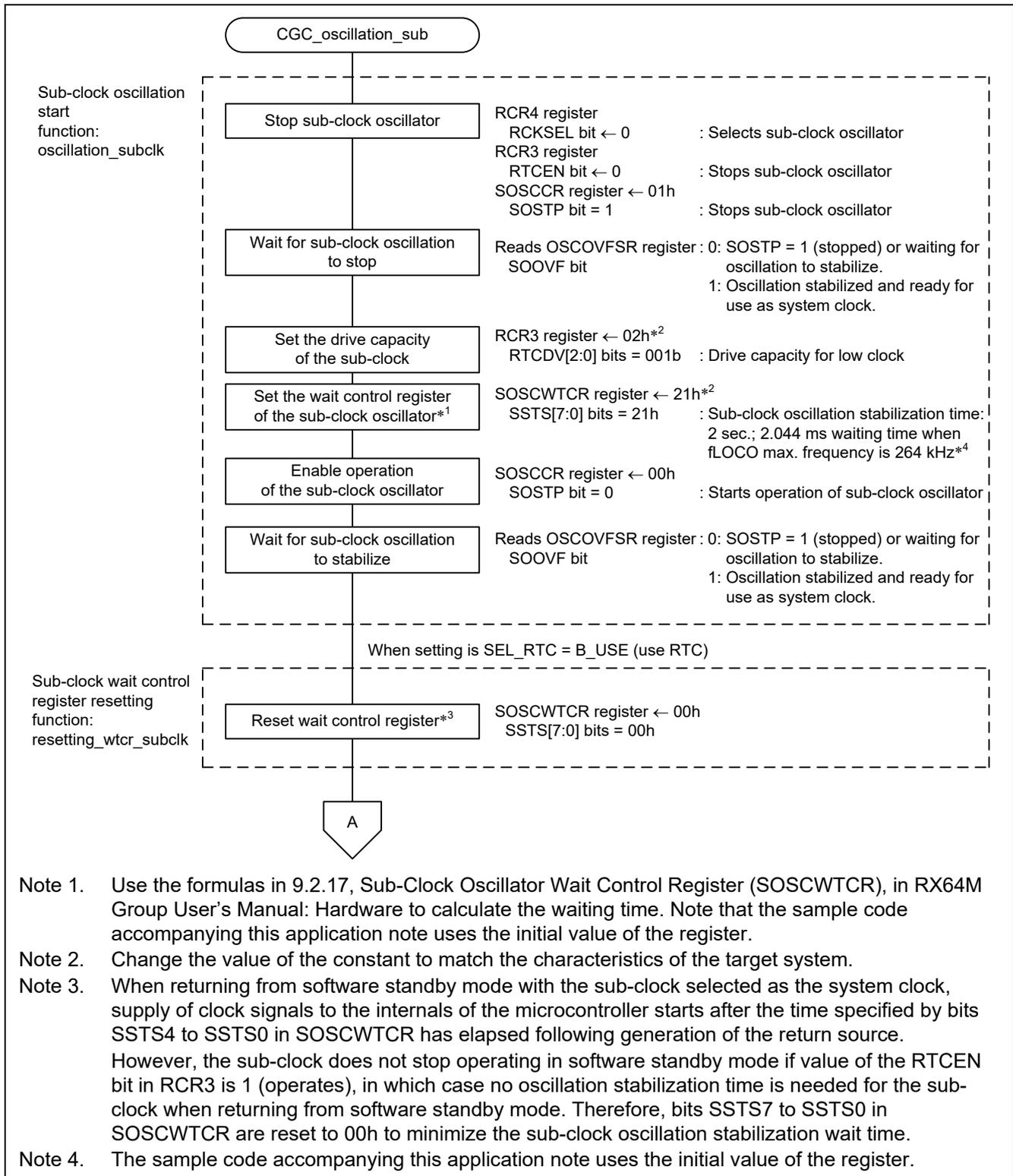


Figure 3.9 Sub-clock Oscillation Enable (1/2)

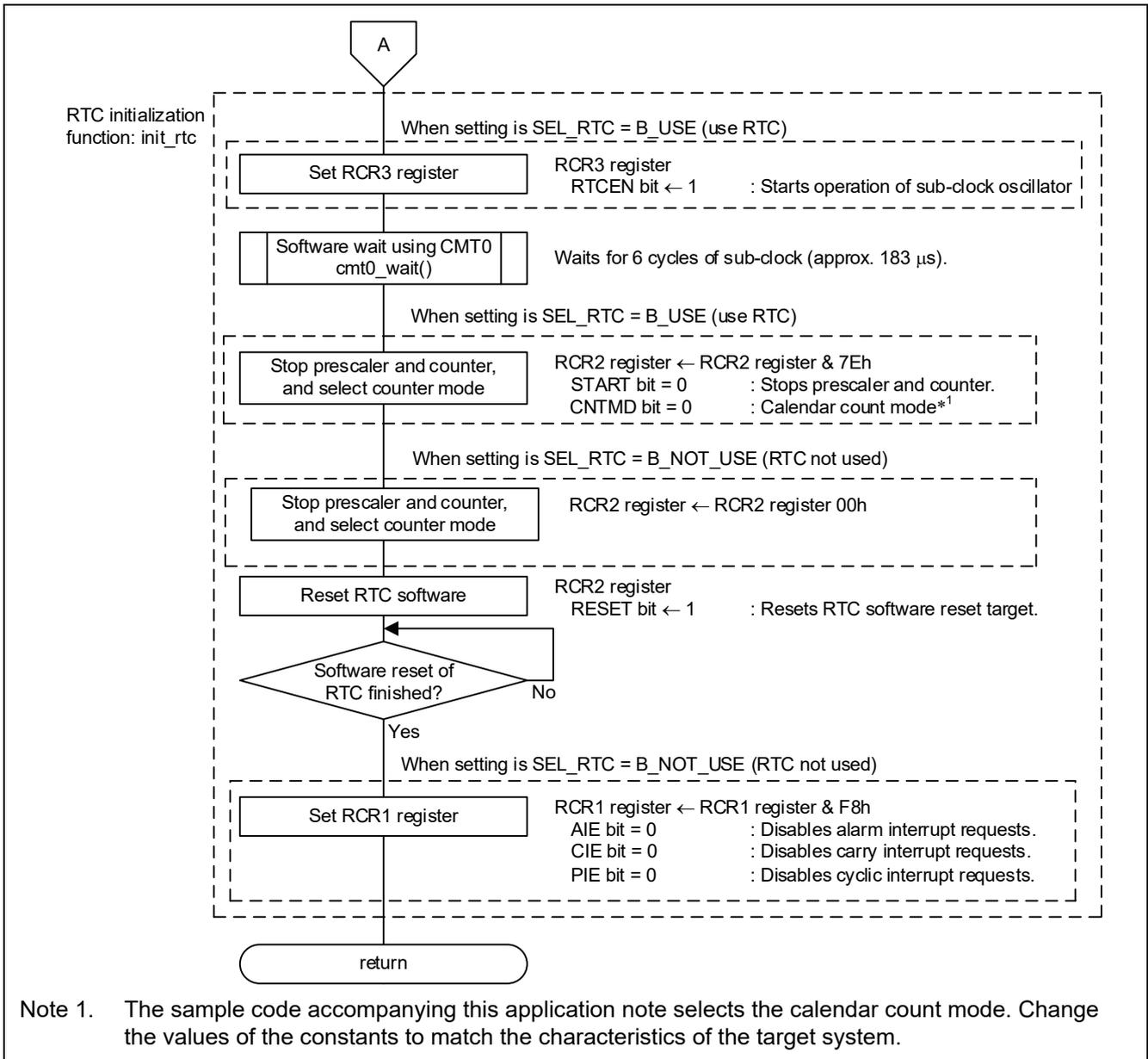


Figure 3.10 Sub-clock Oscillation Enable (2/2)

### 3.10.9 Sub-clock Disable

Figure 3.11 is a flowchart of the processing for stopping the sub-clock.

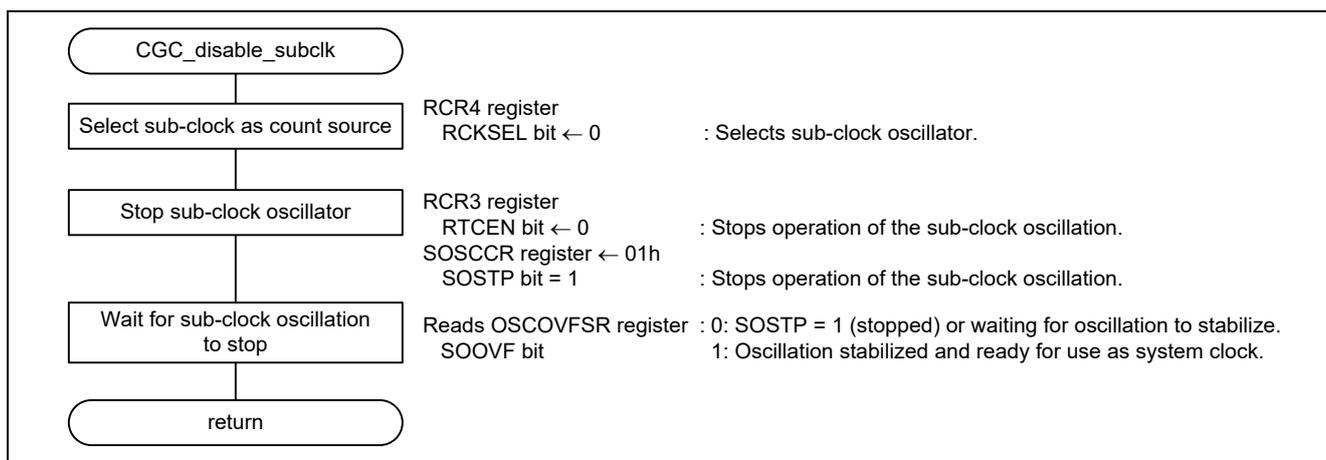
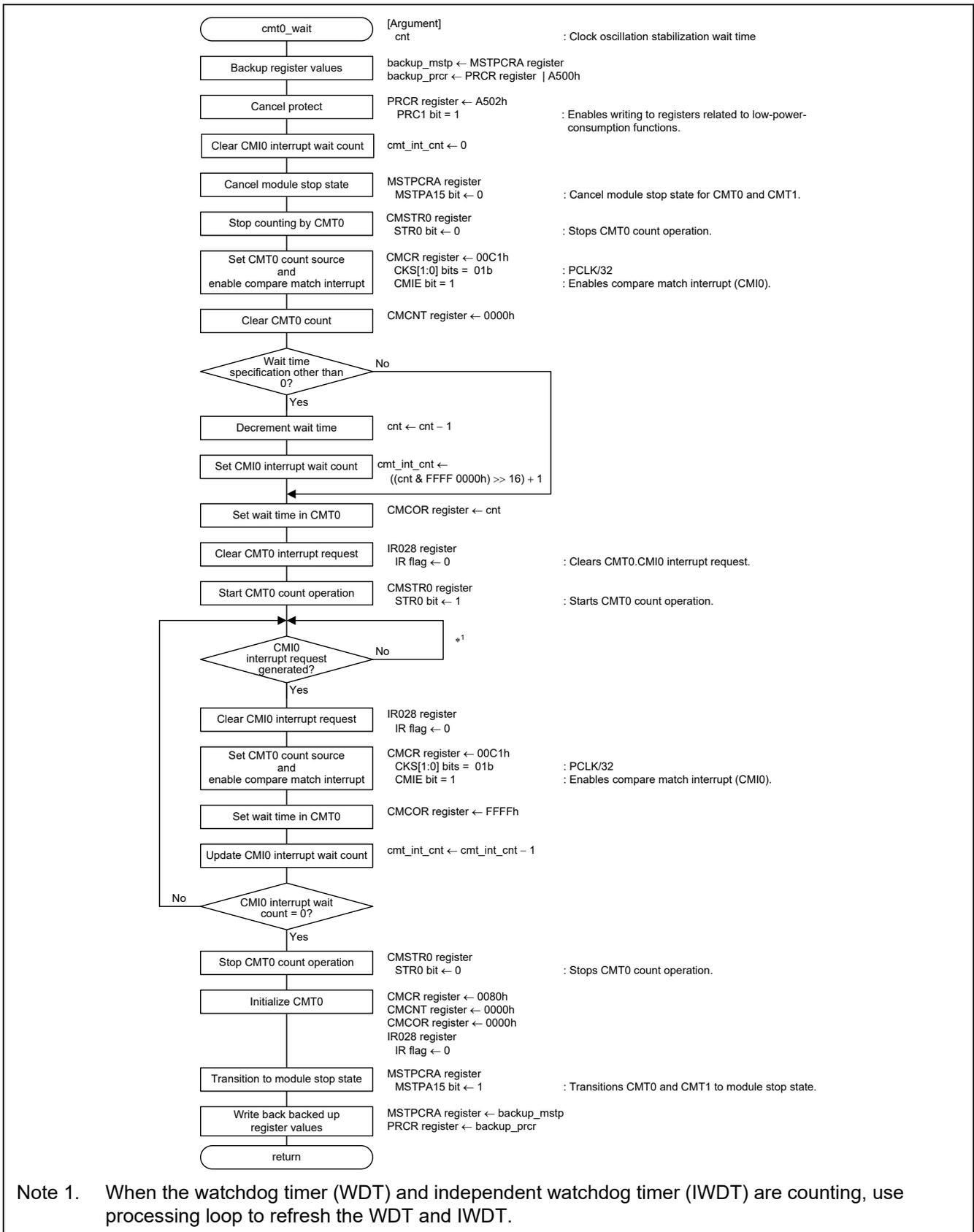


Figure 3.11 Sub-clock Disable

3.10.10 Software Wait Cycles Using CMT0

Figure 3.12 is a flowchart of the processing for implementing a software wait using CMT0.



Note 1. When the watchdog timer (WDT) and independent watchdog timer (IWDT) are counting, use processing loop to refresh the WDT and IWDT.

Figure 3.12 Software Wait Cycles Using CMT0

### 4. Importing a Project

The sample code is provided as the e<sup>2</sup> studio project. This section describes importing a project into the e<sup>2</sup> studio and CS+. After importing a project, confirm that the build settings and the debug settings are correct.

#### 4.1 Importing a Project into the e<sup>2</sup> studio

Follow the steps below to import your project into the e<sup>2</sup> studio.  
(Windows/dialogs may differ depending on the e<sup>2</sup> studio version used.)

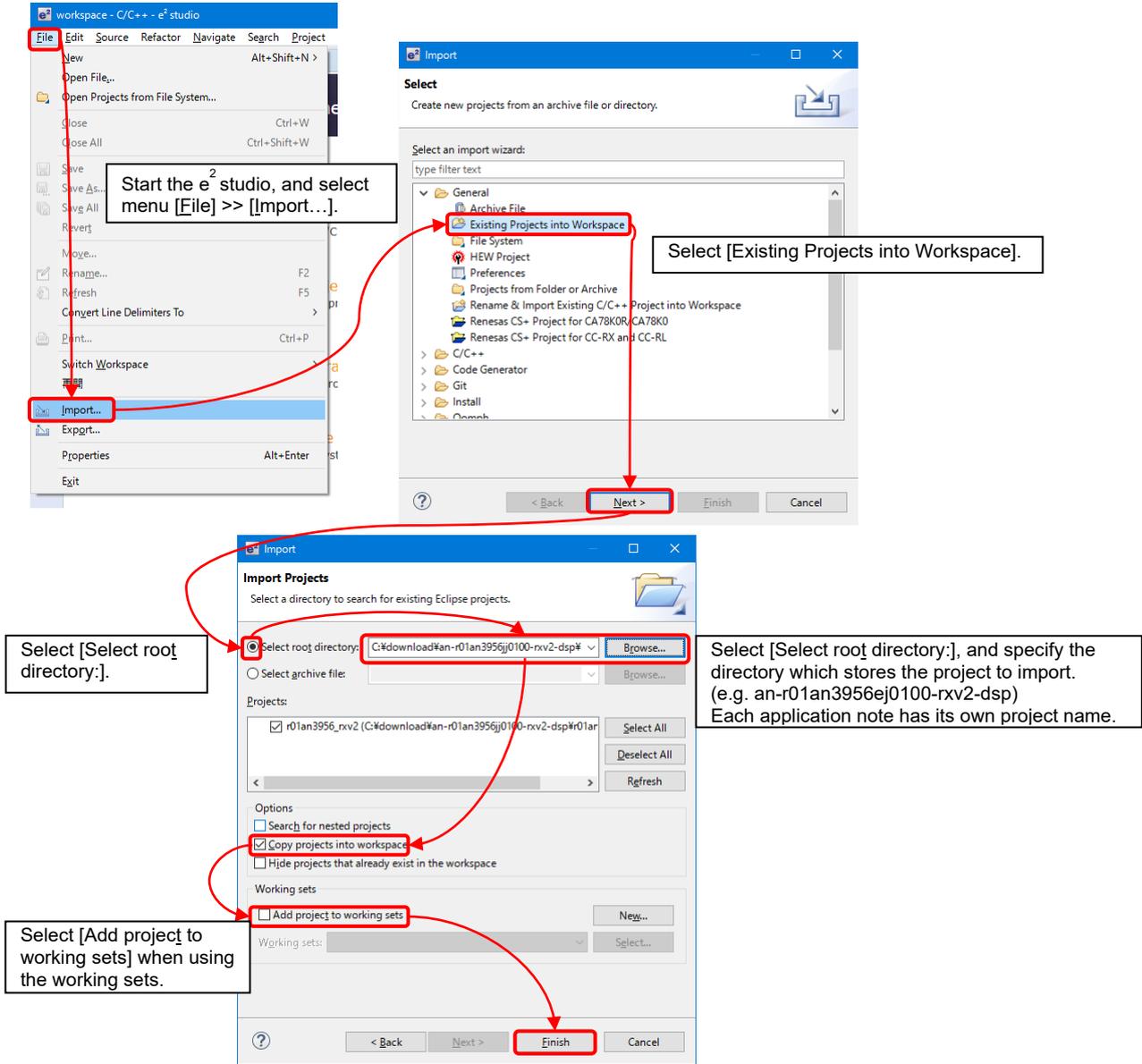


Figure 4.1 Importing a Project into the e<sup>2</sup> studio

### 4.2 Importing a Project into CS+

Follow the steps below to import your project into CS+. (Windows/dialogs may differ depending on the CS+ version used.)

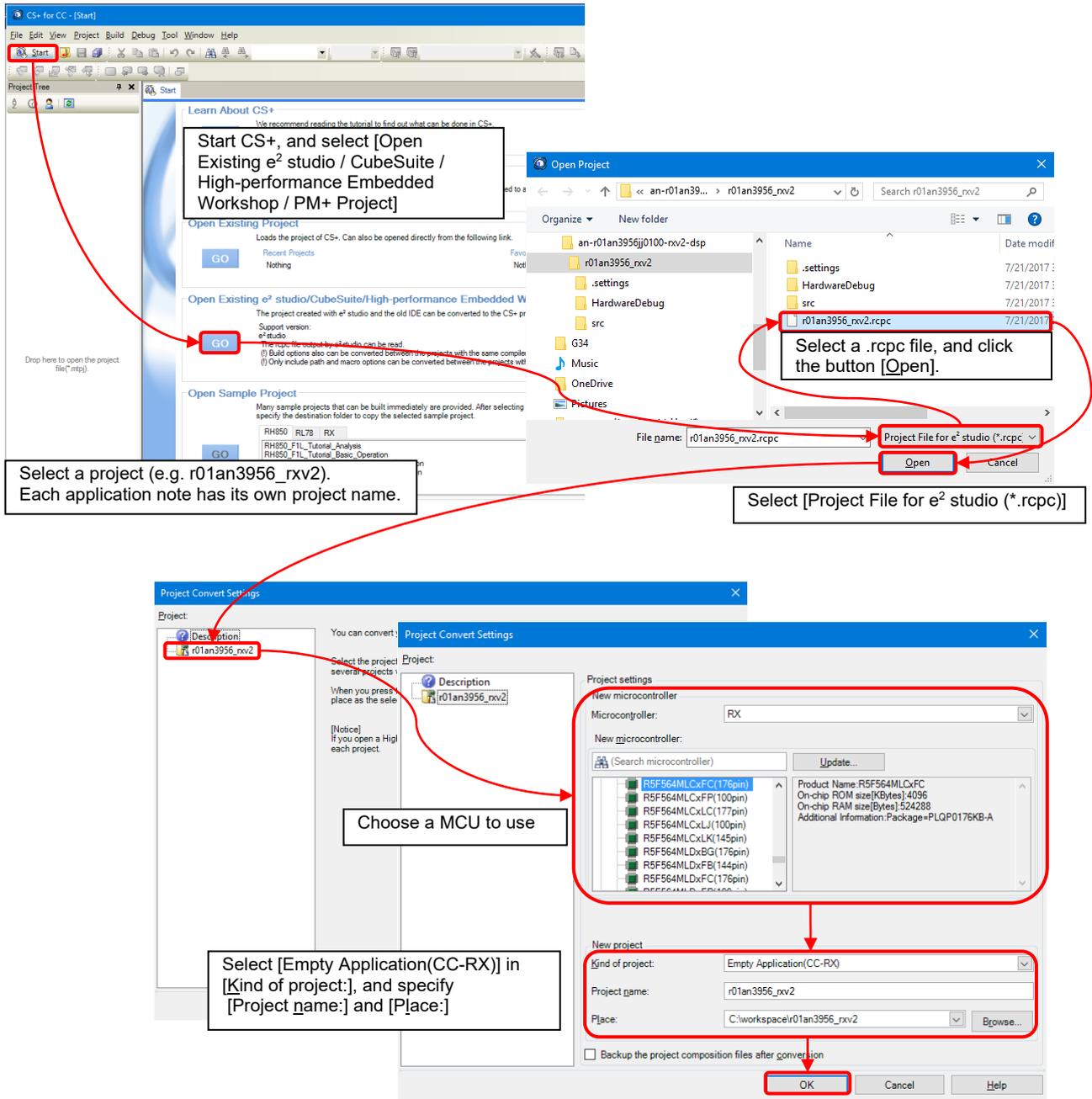


Figure 4.2 Importing a Project into CS+

## 5. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

## 6. Reference Documents

User's Manual: Hardware

RX64M Group User's Manual: Hardware (R01UH0377)

(The latest version can be downloaded from the Renesas Electronics website.)

Technical Update/Technical News

(The latest version can be downloaded from the Renesas Electronics website.)

User's Manual: Development Tools

RX Family CC-RX Compiler User's Manual (R20UT3248)

(The latest version can be downloaded from the Renesas Electronics website.)

## Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Aug.07.19	-	First edition issued
1.10	July.19.19	6	Table 2.1 Operation Confirmation Conditions, changed.
		10	3.4 Section Configuration, added.
		11	Table 3.7 Constants (User Changeable) Used by Sample Code (1/2), changed.
		12	Table 3.8 Constants (User Changeable) Used by Sample Code (2/2), changed.
		13	Table 3.9 Constants (Non User Changeable) Used by Sample Code, changed.
		27	Figure 3.10 Sub-clock Oscillation Enable, corrected.
		29, 30	4. Importing a Project, added.
		Program	<ul style="list-style-type: none"> <li>Added section setting of ECCRAM</li> <li>Changed the path of iodefine.h</li> <li>Changed the following macro definition name            MAIN_CLOCK_Hz -&gt; MAIN_CLOCK_HZ            SUB_CLOCK_Hz -&gt; SUB_CLOCK_HZ            FREQ_16MHz -&gt; FREQ_16MHZ            FREQ_18MHz -&gt; FREQ_18MHZ            FREQ_20MHz -&gt; FREQ_20MHZ</li> <li>Bug fix of init_rtc function            Fixed the bug that can not write the AIE bit of RCR1 register correctly in the init_rtc function.            In the program before modification, an infinite loop may occur because the AIE bit of the RCR1 register can not be written correctly.</li> </ul>
1.11	Feb. 1. 21	6	Table 2.1 Integrated development environment, C compiler, iodefine.h and Sample code version, changed.
		27	Figure 3.10 Subclock Oscillation Enable (2/2), changed.
		program	Technical update TN-RX*-A236B/E, supported.

## General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

### 1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

### 2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

### 3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

### 4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

### 5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

### 6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).

### 7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

### 8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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